

SMTA Press Release

**For more info contact:
Tanya Martin
952-920-7682
tanya@smta.org**



For immediate release – July 20, 2017

**SMTA International Technical Program Expands,
Includes Research from HDPUG and AREA Consortium**

Minneapolis, MN – SMTA announces an expanded program for the final day of the SMTA International Conference, September 17 - 21, 2017 in Rosemont, Illinois. In addition to the Lead-Free Symposium, the technical committee expanded the Thursday program to four concurrent tracks. The three additional tracks will focus on Advanced Packaging Technology, Manufacturing Excellence, and Inspection Technologies.

The Advanced Packaging Technology track will tackle issues such as 2.5D Packaging, Embedded Power Electronics, and Warpage. Presentations by Fraunhofer IZM, I3 Electronics, Nokia, Intel and more are highly anticipated.

The Manufacturing Excellence track includes research on cleaning, conformal coating, as well as recent developments from the HDPUG Consortium.

The Inspection Technologies track includes a full session on counterfeit component mitigation in addition to other areas like solder paste volume measurement, high volume manufacturing, conformal coating, and supply chain issues.

The Lead-Free Symposium opens with recent findings from the AREA Consortium. The other sessions in the track cover Screen Printing, Reliability and Performance of Lead-Free Interconnections, and Innovation for High Reliability Electronics.

For more information on SMTA International please contact SMTA Executive Director Tanya Martin: tanya@smta.org or 952-920-7682 or visit <https://www.smta.org/smtai/>.

SMTA - A Global Association Working at a Local Level

The SMTA membership is an international network of professionals who build skills, share practical experience and develop solutions in electronic assembly technologies, including microsystems, emerging technologies, and related business operations.

-End-